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Generative AI for Analog/RF Integrated Circuit Design and Netlist Synthesis: Evolving Methodologies and Emerging Applications

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ABSTRACT Electronic Design Automation (EDA) in analog Integrated Circuits (ICs) continues to be a critical research area, yet its widespread adoption significantly lags behind its digital counterpart due to inherent complexities. This extended systematic review updates recent contributions in the last five years, specifically highlighting cutting-edge methods that address persistent domain-specific challenges such as data scarcity, efficient topology exploration, robust parameter optimization considering process-voltage-temperature (PVT) variations, and accurate layout parasitic management. Our primary objective is to equip researchers new to this rapidly evolving domain with a comprehensive collection of references, a refined understanding of current challenges, and practical application guidelines. We provide an in-depth methodological review of state-of-the-art machine learning (ML) and generative AI approaches—including Graph Neural Networks (GNNs), Large Language Models (LLMs), and Variational Autoencoders (VAEs)—which are increasingly applied across various analog circuit design tasks, from topology synthesis to parameter sizing and validation. Notably, this survey expands on previous works by integrating discussions on newer, comprehensive frameworks like FALCON and MenTeR, which introduce end-to-end design, multi-agent workflows, and advanced layout-aware optimization. To the best of the authors' knowledge, this is the second review after [1] to comprehensively explore these latest applications of generative AI models in analog IC circuit design, charting their evolution and impact. We conclude by identifying key future research directions, emphasizing few-shot learning, multi-modal AI, and advanced multi-agent systems to further simplify human-tool interaction and guide design space exploration for industrial-scale analog ICs.

INDEX TERMS Analog integrated circuits (ICs), electronic design automation (EDA), generative artificial intelligence (GenAI), graph neural networks (GNNs), large language models (LLMs), machine learning (ML), netlist synthesis, parameter optimization, layout-aware sizing, topology synthesis, variational autoencoders (VAEs).

I. INTRODUCTION

THE escalating complexity and diverse performance requirements of modern analog systems underpin advancements in crucial technologies such as generative AI, 5G/6G communication, and quantum computing. "analog genie" These demands necessitate full-flow automation to effectively manage the intricate trade-offs between numerous performance parameters, a task where traditional manual approaches are notoriously time-consuming and heavily reliant on scarce expert knowledge. While digital design automation has witnessed extensive development and widespread adop-

tion across both industry and academia, the automation of analog IC design continues to face significant challenges.

Researchers have made concerted efforts to automate various stages of the analog design flow "genAI paper". Conventionally, the process is segmented into three primary areas at the circuit level: topology selection, circuit sizing, and layout generation, often with complex feedback loops, as clearly shown in Fig. 1. Although remarkable progress has been achieved in layout generation tools, such as MAGICAL and ALIGN, and in certain aspects of digital IC design with generative AI, the development of scalable and robust solu-

tions for analog circuit sizing and comprehensive topology design remains a formidable challenge. Furthermore, a truly practical automation flow at each stage must inherently account for the interdependencies across design stages^{5,6,7 from genAI paper}; for instance, the initial selection of a topology must proactively consider potential layout parasitics and their subsequent impact on performance metrics.

The fundamental challenge arises from the intricate design complexities of analog ICs. Unlike digital ICs that can be universally and hierarchically abstracted into Boolean logic representations and easily described with high-level hardware description languages (e.g., Verilog and VHDL) or programming languages (e.g., C), analog ICs remain intractable to such abstraction due to their lack of systematic hierarchical representation and the heuristic and knowledge-intensive nature of their design process [1]. This makes automating analog IC design using programming languages similar to those for digital ICs extremely difficult. As such, domain experts have followed a longstanding manual flow to design analog ICs. This process involves a number of time-consuming stages, such as selecting/creating an existing (new) circuit topology (i.e., defining the connections between devices), optimizing device parameters based on the topology to achieve desired performance, and designing the physical layout of the optimized circuit for manufacturing. Importantly, the topology generation stage is the foundation and most creative part of the analog IC design process, posing a formidable and perennial challenge to design automation. Addressing it is the key to accelerating the development of analog ICs.

In response to these challenges, machine learning (ML) has emerged as a promising solution. Learning-based methods, which leverage simulation data for training, offer more efficient design space exploration. ML techniques can be applied individually or in combination to facilitate decision-making, function approximation, and black-box optimization. Recent breakthroughs in generative AI, a subset of ML, have presented transformative opportunities to expedite these conventional design flows. Models such as Graph Neural Networks (GNNs) have shown significant advantages for handling graph-structured circuit data, while Variational Autoencoders (VAEs) are being explored to learn underlying data distributions for tasks like topology optimization. Furthermore, Large Language Models (LLMs), traditionally used for natural language processing, have demonstrated remarkable adaptability to large-scale design problems, including layout automation, optimization, and topology generation.

Despite these advances, many prior studies on ML-driven analog circuit design have often focused on isolated sub-tasks or simple, homogeneous circuits, overlooking the complexities of real-world heterogeneous systems. *"AI Circuit*, The persistent lack of comprehensive, generic, and diverse datasets with robust metrics has been a major impediment to thoroughly evaluating and improving ML algorithms in the analog domain. Moreover, many early generative AI approaches for topology generation were limited in scale, producing single types of small or conventional ICs, or suffered

from ambiguous representations. This has encouraged the recent works to try bridging these gaps by proposing more holistic frameworks that integrate multiple design stages, leverage multi-agent systems, and incorporate layout-aware optimization to better reflect practical design scenarios. *"AI Circuit*, *FALCON*, *MenTeR* *"ADO-LLM"*, *"Analog-GENIE"*, *"AMP-AGENT"*

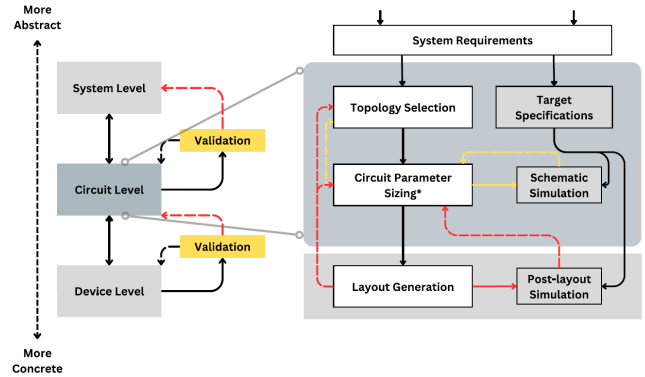


FIGURE 1. Analog design automation flow, focusing on circuit-level automation. Dashed lines indicate dependencies between design stages.

This paper aims to bridge these gaps by providing an updated and expanded systematic review of generative AI applications in analog IC design. We particularly focus on recent developments that push the boundaries of automation across the entire design pipeline, addressing shortcomings such as data scarcity, limited scalability, and inadequate layout awareness. Specifically, this review will integrate analysis of groundbreaking new frameworks like:

- **AnalogGenie:** A generative engine focused on the automatic discovery of diverse, large, and unseen analog circuit topologies using a scalable sequence-based graph representation and an augmented dataset.
- **AnalogCoder:** The first training-free LLM agent that designs analog circuits through Python code generation, employing feedback-enhanced flows and a circuit tool library.
- **SPICEPilot:** A framework leveraging LLMs to generate Python-based SPICE code, addressing data scarcity by automating dataset creation and providing standardized benchmarking.
- **AnalogXpert:** An LLM-based agent for subcircuit-level SPICE code generation that incorporates circuit design expertise through a proofreading strategy for iterative error correction.
- **MenTeR:** A fully-automated multi-agent workflow for end-to-end RF/Analog circuit netlist design, emphasizing specification understanding, collaborative optimization, and test bench validation through Chain-of-Stage reasoning and Diagram-Aware RAG.
- **FALCON:** A unified ML framework enabling fully automated, specification-driven analog circuit synthesis through performance-driven topology selection, GNN-

based parameter inference, and layout-constrained optimization, validated with industrial-grade simulations.

- **AICircuit:** A multi-level dataset and benchmark that facilitates the development and evaluation of ML algorithms for both homogeneous and heterogeneous analog and RF circuit designs.
- **AMSNet:** A netlist dataset for Analog and Mixed-Signal (AMS) circuits, which consists of 734 topologies and has been utilized for LLM-based AMS circuit auto-design and netlist generation.
- **AnalogCoderPro:** A training-free, end-to-end multi-modal LLM framework that unifies topology generation and device sizing. It advances AnalogCoder by incorporating a multimodal diagnosis-and-repair feedback loop that uses simulation logs and waveform images for autonomous error correction.

These frameworks represent significant strides toward achieving holistic, human-competitive, and even superhuman capabilities in analog IC design.

The main contributions of this paper are as follows:

- **Comprehensive Survey of Recent Advancements:** Examine and compare recent advancements in generative AI for analog circuit design, with a particular focus on evolving techniques that address topology exploration, scalable parameter sizing, robust PVT variations, and realistic layout parasitics.
- **Methodological Review of State-of-the-Art Techniques:** Provide a methodological review of state-of-the-art generative AI techniques applied in analog circuit design automation, including Graph Neural Networks (GNNs), Large Language Models (LLMs), and Variational Autoencoders (VAEs), showcasing their latest applications and interconnections.
- **Analysis of Novel Comprehensive Frameworks:** Integrate and analyze new, comprehensive frameworks such as FALCON, MenTeR, AnalogGenie, AnalogCoder, SPICEPilot, and AnalogXpert, which were not thoroughly covered in previous surveys, providing insights into their unique contributions and synergistic potential.
- **Practical Resource Compilation:** Collect and synthesize abundant resources, open-source codes, and application guidelines to serve as a practical reference for researchers new to or advancing within the field of analog circuit automation.

The remainder of this paper is structured as follows: section II summarizes and compares previous review papers in terms of their automation scope and the ML techniques covered, highlighting the gaps addressed by this work. section III introduces fundamental IC design challenges and outlines how these challenges shape the automation task for generative AI. section IV provides the fundamentals of generative AI relevant to recent research, including detailed discussions on GNNs, LLMs, and VAEs. section V comprehensively compares significant research works, focusing on their method-

ologies, key problems they attempt to solve, and their contributions to the evolving landscape of analog design automation. Finally, section VI outlines future research directions and challenges for large-scale industrial adoption, including discussions on multi-agent systems and multi-modal AI.

II. RELATED WORKS AND SURVEY LANDSCAPE

The rapid evolution of Artificial Intelligence (AI) and foundation models has spurred numerous systematic reviews aimed at capturing the state-of-the-art in Electronic Design Automation (EDA) "To add all previous survey papers".

This section summarizes the scope of previous survey papers and highlights the critical gaps that this work addresses, particularly concerning the application of generative AI to the complex domain of analog integrated circuits (ICs).

A. TAXONOMY OF PRIOR AI FOR EDA SURVEYS

Existing reviews on AI for EDA can generally be categorized into two major types based on the AI paradigm they cover "A survey of circuit foundation models":

1) Supervised Predictive AI Techniques

This category represents the mainstream of earlier AI for EDA solutions "circuit foundation model, generative AI for analog IC", focusing on supervised predictive models tailored for specific tasks, such as early prediction of design quality metrics (e.g., timing, area, power). These works have been extensively studied and covered in earlier surveys "put all previous surveys". However, they often fall short in addressing the unique challenges of analog IC design, which requires more than just predictive accuracy. The need for creativity in topology generation and the handling of continuous parameter spaces are aspects that these surveys do not fully explore.

2) Foundation AI Techniques (Circuit Foundation Models - CFMs)

This emerging trend focuses on models characterized by pre-training on large datasets followed by fine-tuning for specific applications, enhancing generalization and generative capabilities "put survey of circuit foundation models here". The concept of Circuit Foundation Models (CFMs) encompasses two primary approaches: encoder-based and decoder-based models. Encoder-based models, such as Graph Neural Networks (GNNs), are adept at learning representations from graph-structured data, making them suitable for tasks like topology classification and parameter prediction. Decoder-based models, including Variational Autoencoders (VAEs) and Large Language Models (LLMs), excel in generating new designs by learning the underlying distribution of existing circuits.

Most recent surveys on second type CFMs have primarily focused on decoder-based models, specifically Large Language Models (LLMs) for EDA "search of relevant papers in the survey paper". This focus reflects the immense generative potential demonstrated by LLMs in areas like Hardware De-

scription Language (HDL) code generation, verification, and debugging "search of relevant papers in the survey paper".

B. COMPARISON OF COVERAGE AND GAPS

A direct comparison reveals that existing surveys often suffer from limitations in scope, depth of analog coverage, or model inclusivity "pick relevant papers from previous surveys".

TABLE 1. Comparison of Survey Focus and Gaps

Survey	ML/AI Techniques	Gaps Addressed
Traditional Analog Surveys	Bayesian Optimization (BO), Evolutionary Algorithms (EA), Deep Neural Networks (DNNs), Convolutional Neural Networks (CNNs)	Lack coverage of generative AI (LLMs, VAEs) and end-to-end integration; often overlook post-layout effects
LLM-EDA	Decoder LLMs	Lacks encoders (GNNs); digital bias; limited analog focus
Recent Perspectives	Encoder/Decoder LLMs	Missing latest GenAI & multi-agent analog applications

Specific Gaps in Previous Literature:

1) Model Inclusivity:

Model inclusivity addresses whether a survey covers the necessary range of AI paradigms critical for analog circuit automation, specifically encompassing both generative and predictive models. The majority of LLM-focused surveys covered only decoder-based LLMs. This survey, in contrast, incorporates both encoder-based GNNs (used for generalized circuit representation learning and predictive tasks like design quality evaluation) and decoder-based LLMs (used for generative tasks) into a unified CFM framework.

- **CFM Survey:** (to adjust the link) This work is highly model-inclusive. It systematically defines and categorizes all works within the foundation model paradigm into two primary types: encoder-based methods (which typically learn generalized representations for predictive tasks, e.g., Graph Neural Networks (GNNs)) and decoder-based methods (which leverage Large Language Models (LLMs) for generative tasks). This approach inherently covers the diverse model architectures used across the digital and analog EDA flows.
- **LLM for EDA Survey (The Leak):** The primary limitation of this survey is its exclusive focus on Large Language Models (LLMs), which are decoder-based foundation models. This narrow scope results in a critical omission of foundational encoder-based methods. Many breakthroughs in analog automation rely on non-LLM techniques, such as Graph Neural Networks (GNNs) and Variational Autoencoders (VAEs), which are fundamental for tasks like parasitic modeling and topology generation (e.g., CktGNN). By concentrating solely on LLMs, this survey overlooks a substantial and active segment of foundational analog AI research.

- **Analog AI Survey:** This paper aims to provide a comprehensive methodological review encompassing GNNs, LLMs, and VAEs as applied to analog circuit sizing and automation.

2) Analog Depth:

Analog circuit design poses unique challenges, such as complexity due to diverse components, intricate interconnections, and the necessity of direct device-level representation, unlike the high-level abstraction available in digital design.

- **AnalogGenAI Survey:** The AnalogGenAI survey offers the deepest focus, dedicated entirely to analog IC design methodologies and applications. It effectively highlights core analog challenges including data scarcity, topology exploration, PVT variations, and layout parasitics. This survey is particularly rich in techniques for circuit sizing, reinforcement learning, and layout-aware automation. However, much of the research discussed focuses on relatively simple circuits like Op-Amps, with complex systems such as PLLs and power amplifiers being comparatively underexplored.
- **CFM and LLM4EDA Surveys:** Both CFM and LLM4EDA dedicate sections to analog circuits. The CFM survey lists recent works like AnalogGenie, AnalogCoder, and LaMAGIC. The LLM4EDA survey details contributions in initial specification/topology selection, schematic design/simulation (e.g., AnalogCoder, ADO-LLM, LaMAGIC), and layout design (e.g., LLANA, LayoutCopilot).

Gap and Contribution: While previous surveys acknowledge the analog domain, detailed coverage of advanced generative capabilities, especially those focusing on scalable and flexible topology discovery, is often summarized. Our survey will emphasize recent breakthroughs that address fundamental analog design difficulties:

- **Scalable Topology Discovery:** We highlight approaches like AnalogGenie, which addresses scalable and general analog design by broadening the variety of ICs and increasing device counts. AnalogGenie introduces a sequence-based, pin-level graph representation to efficiently capture large analog circuit topologies, enabling the discovery of diverse and unseen topologies.
- **Practical Topology Synthesis:** We examine specialized LLM agents like AnalogXpert, which moves toward practical topology synthesis by formulating it as a subcircuit-level SPICE code generation problem. AnalogXpert achieves significantly higher success rates (40% on synthetic data, 23% on real data) compared to baselines like AnalogCoder (8% and 6%, respectively) due to its use of a subcircuit library and a human experience-based proofreading strategy.

3) Emerging Frameworks and Methodologies

Despite the advancements in analog design automation, several challenges remain unaddressed. These include:

- **End-to-End Automation:** End-to-end automation, spanning from specifications to layout-aware netlists, is identified as a critical future direction across all three existing surveys.

Gap and Contribution: The current literature often tackles topology generation and parameter optimization as separate, sequential stages, which can lead to suboptimal results when inherent topological constraints are ignored during sizing. Our survey highlights new efforts that unify these stages:

- **Unified Generation and Optimization:** AnalogCoder-Pro is introduced as a training-free, multimodal LLM framework designed for end-to-end analog circuit design, jointly performing topology generation and device sizing. It focuses on transforming natural-language design objectives into optimized netlists.
- **Layout-Constrained Synthesis:** FALCON unifies topology selection, parameter inference, and layout-aware optimization in a single end-to-end pipeline. It guides parameter inference using a differentiable layout cost, integrating schematic and physical considerations.
- **Multi-Agent and Feedback Systems:** The use of autonomous agents and sophisticated feedback loops is crucial for handling the complexity and iterative nature of analog design. The LLM4EDA survey notes the trend toward LLM autonomous agents that iteratively improve code quality by incorporating feedback. It specifically mentions Layout-Copilot as an LLM-powered multi-agent collaborative framework for analog layout design. AnalogCoder employs a feedback-enhanced design flow to refine generated circuits based on functional checks and simulation results.

Gap and Contribution: Recent advancements incorporate multi-modal inputs and highly specialized agents to improve robustness and efficiency beyond basic feedback loops:

- **Multi-Modal Diagnosis:** AnalogCoder-Pro advances the feedback loop by incorporating a multimodal diagnosis-and-repair feedback loop that utilizes simulation error messages and waveform images to autonomously correct design errors.
- **Specialized Multi-Agent Systems:** MenTeR proposes a fully-automated multi-agent workflow integrated into an end-to-end analog design framework. It uses specialized agents for specification understanding, design refinement via Chain-of-Stage (CoS) reasoning, and diagram-aware retrieval, demonstrating significant performance improvements over single-agent approaches, even tackling complex circuits like the CMOS Bandgap Reference. Similarly, AmpAgent is an LLM-based multi-agent system specifically for multi-stage am-

plifier schematic design.

- **Data Scarcity Solutions:** The lack of large, high-quality, and publicly available analog circuit datasets remains a fundamental bottleneck.

All three existing surveys recognize this challenge. The CFM survey explicitly discusses synthetic dataset generation and advanced data augmentation techniques as necessary paths forward. The AnalogGenAI survey advocates for the creation of open-source datasets and testbenches like AICircuit.

Gap and Contribution: Our survey highlights critical recent efforts focused on generating large-scale, automated, and multi-modal analog datasets, which are essential for training robust foundation models.

- **Generative Dataset Creation:** We discuss new automated frameworks designed to extract data at scale. AnalogGenie addressed this gap by building an extensive dataset of over 3,000 distinct analog circuit topologies with diverse functionalities, expanded by over 70x using data augmentation.
- **Automated Schematic-to-Netlist Extraction:** We review frameworks dedicated to overcoming the image-to-netlist conversion barrier. Masala-CHAI is a fully automated framework leveraging LLMs and custom deep network models to generate SPICE netlists from schematic images, resulting in the largest curated open-source dataset of ~7,500 SPICE netlists from textbooks. Similarly, AM-Snet 2.0 uses deep-learning-based image instance segmentation for robust net detection to generate netlists and subsequently reconstruct digital schematics, overcoming the limitations of previous heuristic methods on noisy schematics. These tools directly address the deficiency of SPICE netlist data compared to digital HDL code and SPICE-Pilot (LLM-generated SPICE datasets).

By focusing on these specific advancements—particularly the deep integration of multi-modal data, multi-agent reasoning, unified topology-sizing optimization, and large-scale dataset generation—our survey provides a current and comprehensive understanding of the Generative AI landscape for complex analog circuit design, building upon and extending the scope of the existing literature.

By incorporating over 130 relevant works, spanning both predictive (encoder-based) and generative (decoder-based) methodologies, this survey provides a comprehensive collection of resources and application guidelines for researchers targeting industrial-scale analog IC design challenges.

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Please note that the $\{subequations\}$ environment in \LaTeX will increment the main equation counter even when there are no equation numbers displayed. If you forget that,

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Do not use `\nonumber` inside the `{array}` environment. It will not stop equation numbers inside `{array}` (there won't be any anyway) and it might stop a wanted equation number in the surrounding equation.

III. SOME COMMON MISTAKES

The word "data" is plural, not singular. The subscript for the permeability of vacuum μ_0 is zero, not a lowercase letter "o." The term for residual magnetization is "remanence"; the adjective is "remanent"; do not write "remnance" or "remnant." Use the word "micrometer" instead of "micron." A graph within a graph is an "inset," not an "insert." The word "alternatively" is preferred to the word "alternately" (unless you really mean something that alternates). Use the word "whereas" instead of "while" (unless you are referring to simultaneous events). Do not use the word "essentially" to mean "approximately" or "effectively." Do not use the word "issue" as a euphemism for "problem." When compositions are not specified, separate chemical symbols by en-dashes; for example, "NiMn" indicates the intermetallic compound $\text{Ni}_{0.5}\text{Mn}_{0.5}$ whereas "Ni–Mn" indicates an alloy of some composition $\text{Ni}_x\text{Mn}_{1-x}$.

Be aware of the different meanings of the homophones "affect" (usually a verb) and "effect" (usually a noun), "complement" and "compliment," "discreet" and "discrete," "principal" (e.g., "principal investigator") and "principle" (e.g., "principle of measurement"). Do not confuse "imply" and "infer."

Prefixes such as "non," "sub," "micro," "multi," and "ultra" are not independent words; they should be joined to the words they modify, usually without a hyphen. There is no period after the "et" in the Latin abbreviation "*et al.*" (it is also italicized). The abbreviation "i.e.," means "that is," and the abbreviation "e.g.," means "for example" (these abbreviations are not italicized).

A general IEEE styleguide is available at <http://www.ieee.org/authortools>.

IV. GUIDELINES FOR GRAPHICS PREPARATION AND SUBMISSION

TABLE 2. Units for Magnetic Properties

Symbol	Quantity	Conversion from Gaussian and CGS EMU to SI ^a
Φ	magnetic flux	1 Mx $\rightarrow 10^{-8}$ Wb = 10^{-8} V·s
B	magnetic flux density, magnetic induction	1 G $\rightarrow 10^{-4}$ T = 10^{-4} Wb/m ²
H	magnetic field strength	1 Oe $\rightarrow 10^3/(4\pi)$ A/m
m	magnetic moment	1 erg/G = 1 emu $\rightarrow 10^{-3}$ A·m ² = 10^{-3} J/T
M	magnetization	1 erg/(G·cm ³) = 1 emu/cm ³ $\rightarrow 10^3$ A/m
$4\pi M$	magnetization	1 G $\rightarrow 10^3/(4\pi)$ A/m
σ	specific magnetization	1 erg/(G·g) = 1 emu/g $\rightarrow 1$ A·m ² /kg
j	magnetic dipole moment	1 erg/G = 1 emu $\rightarrow 4\pi \times 10^{-10}$ Wb·m
J	magnetic polarization	1 erg/(G·cm ³) = 1 emu/cm ³ $\rightarrow 4\pi \times 10^{-4}$ T
χ, κ	susceptibility	1 $\rightarrow 4\pi$
χ_ρ	mass susceptibility	1 cm ³ /g $\rightarrow 4\pi \times 10^{-3}$ m ³ /kg
μ	permeability	1 $\rightarrow 4\pi \times 10^{-7}$ H/m = $4\pi \times 10^{-7}$ Wb/(A·m)
μ_r	relative permeability	$\mu \rightarrow \mu_r$
w, W	energy density	1 erg/cm ³ $\rightarrow 10^{-1}$ J/m ³
N, D	demagnetizing factor	1 $\rightarrow 1/(4\pi)$

Vertical lines are optional in tables. Statements that serve as captions for the entire table do not need footnote letters.

^aGaussian units are the same as cg emu for magnetostatics; Mx = maxwell, G = gauss, Oe = oersted; Wb = weber, V = volt, s = second, T = tesla, m = meter, A = ampere, J = joule, kg = kilogram, H = henry.

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The following list outlines the different types of graphics published in IEEE journals. They are categorized based on their construction, and use of color/shades of gray:

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3) Author photos

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4) Tables

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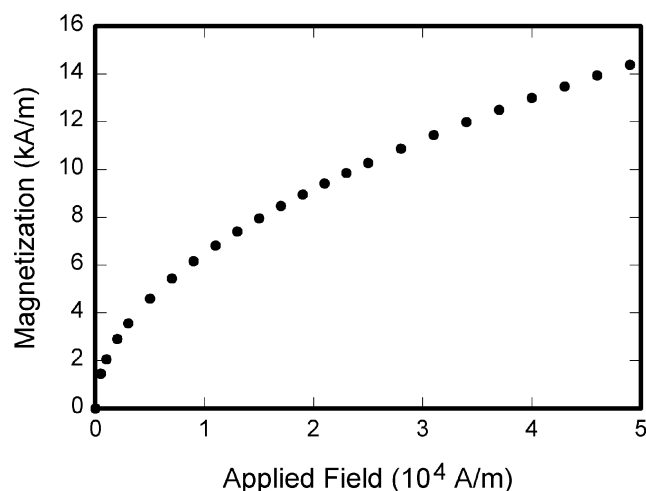


FIGURE 2. Magnetization as a function of applied field. It is good practice to explain the significance of the figure in the caption.

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Most charts, graphs, and tables are one column wide (3.5 inches/88 millimeters/21 picas) or page wide (7.16 inches/181 millimeters/43 picas). The maximum depth a graphic can be is 8.5 inches (216 millimeters/54 picas). When choosing the depth of a graphic, please allow space for a caption. Figures can be sized between column and page widths if the author chooses, however it is recommended that figures are not sized less than column width unless when necessary.

There is currently one publication with column measurements that do not coincide with those listed above. Proceedings of the IEEE has a column measurement of 3.25 inches (82.5 millimeters/19.5 picas).

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1) Figure Axis labels

Figure axis labels are often a source of confusion. Use words rather than symbols. As an example, write the quantity “Magnetization,” or “Magnetization M,” not just “M.” Put units in parentheses. Do not label axes only with units. As in Fig. 1, for example, write “Magnetization (A/m)” or “Magnetization ($A \cdot m^{-1}$),” not just “A/m.” Do not label axes with a ratio of quantities and units. For example, write “Temperature (K),” not “Temperature/K.”

Multipliers can be especially confusing. Write “Magnetization (kA/m)” or “Magnetization (10^3 A/m).” Do not write “Magnetization (A/m) \times 1000” because the reader would not know whether the top axis label in Fig. 1 meant 16000 A/m or 0.016 A/m. Figure labels should be legible, approximately 8 to 10 point type.

2) Subfigure Labels in Multipart Figures and Tables

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